



## *Micro Commercial Components Corp.*

### Products End of Life Notification

Issue date: Sep-7<sup>th</sup>-2008

Last Buy Date :Dec-6<sup>th</sup>-2008

Description and Purpose:

MCC has undergone a review of its core business and products , and determined to discontinue below products:

Discontinued Devices	Possible Replacements
S8A	None
S8B	None
S8D	None
S8G	None
S8J	None
S8K	None
S8M	None



Micro Commercial Components

Micro Commercial Components  
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**Features**

- Lead Free Finish/Rohs Compliant (Note1) ("P" Suffix designates Compliant. See ordering information)
- Low Thermal Resistance
- High Current Capability
- High Temp Soldering: 260°C for 10 Seconds At Terminals
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0 and MSL rating 1

**Maximum Ratings**

- Operating Temperature: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Maximum Thermal Resistance; 8°C/W Junction To Lead

Microsemi Part Number	Device Marking	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
S8A	S8A	50V	35V	50V
S8B	S8B	100V	70V	100V
S8D	S8D	200V	140V	200V
S8G	S8G	400V	280V	400V
S8J	S8J	600V	420V	600V
S8K	S8K	800V	560V	800V
S8M	S8M	1000V	700V	1000V

**Electrical Characteristics @ 25°C Unless Otherwise Specified**

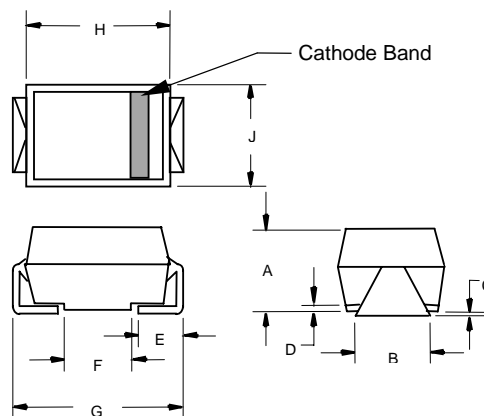
Average Forward Current	$I_{F(AV)}$	8.0A	$T_a = 75^\circ\text{C}$
Peak Forward Surge Current	$I_{FSM}$	300A	8.3ms, half sine
Maximum Instantaneous Forward Voltage	$V_F$	1.20V	$I_{FM} = 8.0A$ ; $T_J = 25^\circ\text{C}^*$
Maximum DC Reverse Current At Rated DC Blocking Voltage	$I_R$	10µA 100µA	$T_J = 25^\circ\text{C}$ $T_J = 100^\circ\text{C}$
Typical Junction Capacitance	$C_J$	150pF	Measured at 1.0MHz, $V_R=4.0V$

\*Pulse test: Pulse width 200 µsec, Duty cycle 2%  
 Note: 1. High Temperature Solder Exemptions Applied, see EU Directive Annex 7.

**S8A  
THRU  
S8M**

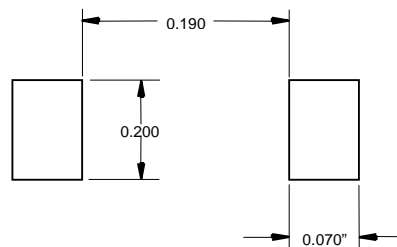
**8 Amp  
Silicon Rectifier  
50 to 1000 Volts**

**DO-214AB  
(HSMC) (Round Lead)**



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.200	.214	5.08	5.43	
B	.177	.203	4.70	5.30	
C	.002	.005	.05	.13	
D	—	.02	—	.51	
E	.047	.056	1.20	1.42	
F	.168	.179	4.27	4.55	
G	.309	.322	7.85	8.18	
H	.239	.243	6.08	6.18	
J	.234	.240	5.95	6.10	

**SUGGESTED SOLDER  
PAD LAYOUT**



# S8A thru S8M

Figure 1  
Typical Forward Characteristics

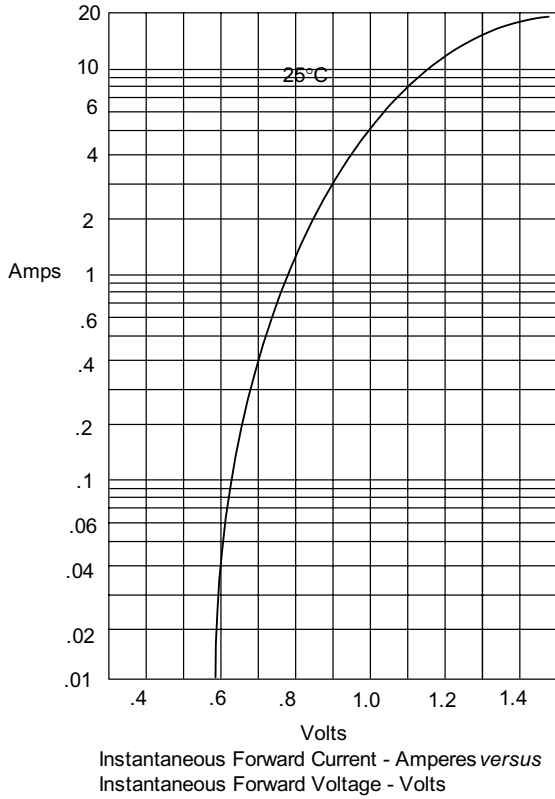


Figure 2  
Forward Derating Curve

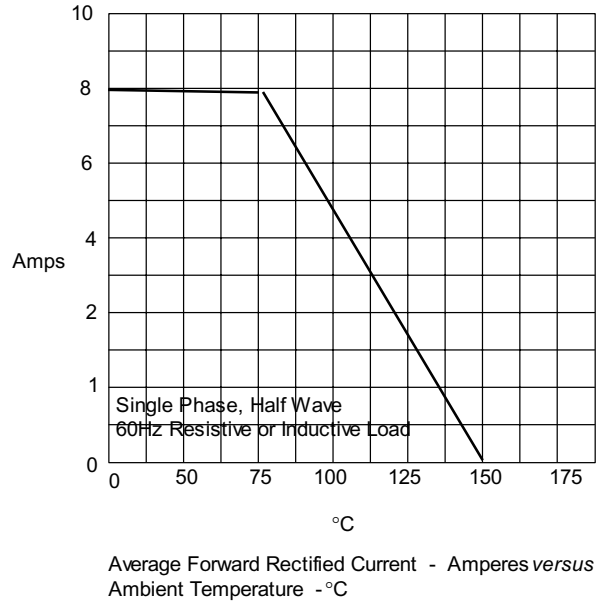
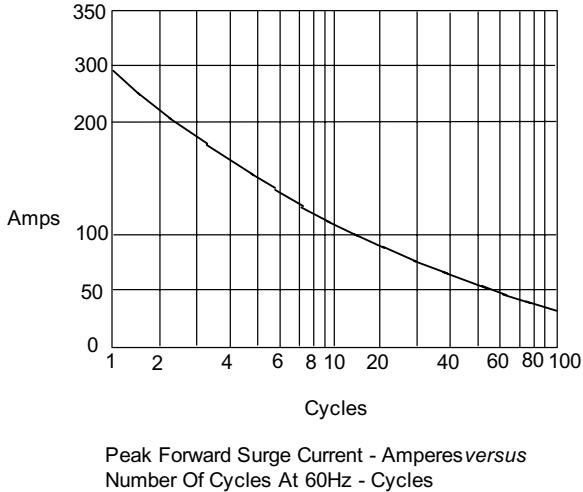


Figure 4  
Peak Forward Surge Current





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## Ordering Information

Device	Packing
(Part Number)-TP	Tape&Reel;1.5Kpcs/Reel

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